

Abstract

An MCM package and a method of manufacturing the package are disclosed. The package includes a first die assembly or die, a wiring substrate, a plastic encapsulation layer, first conductive traces, second conductive traces, conductive bumps, a first dielectric layer and a second dielectric layer. The wiring substrate can accommodate a wiring layer required to be formed over active surfaces of dies and contains multiple complex circuits, which are electrically connected to bond pads on the dies' active surfaces and thus embedded within the package.